

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
7 September 2007 (07.09.2007)

PCT

(10) International Publication Number
WO 2007/099823 A1

(51) International Patent Classification:

B29C 43/50 (2006.01) **H01L 21/56** (2006.01)
C08L 83/04 (2006.01)

(21) International Application Number:

PCT/JP2007/053131

(22) International Filing Date:

14 February 2007 (14.02.2007)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

2006-046872 23 February 2006 (23.02.2006) JP

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(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LV, LY, MA, MD, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, SV, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

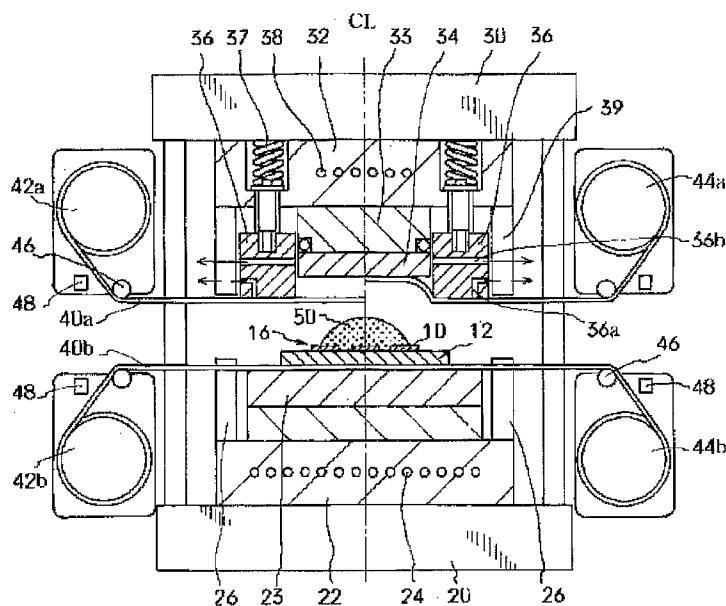
(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, LV, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— with international search report

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: METHOD OF MANUFACTURING A SEMICONDUCTOR DEVICE AND A SEMICONDUCTOR DEVICE PRODUCED THEREBY



(57) Abstract: A method of manufacturing a semiconductor device sealed in a cured silicone body by placing an unsealed semiconductor device into a mold and subjecting a curable silicone composition which is fed into the space between the mold and the unsealed semiconductor device to compression molding, the method being characterized by the fact that the aforementioned curable silicone composition comprises at least the following components: (A) an epoxy-containing silicone and (B) a curing agent for an epoxy resin; can reduce warping of the semiconductor chips and circuit board, and improve surface resistance to scratching.

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